Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays External Options

**Marketing Name / Model**
[List multiple models if applicable.]

- HP EliteDisplay P224 Monitor
- HP EliteDisplay P224 21.5-inch Monitor
- HP P224
- HSD-0024-Q

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

**1.0 Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board<em>1, Control Board</em>1, SPS Board*1</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
</tbody>
</table>
| Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.) | Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain ______  
**NOTE:** Add detailed removal procedures including required tools in the sections 3.1 and 3.2. | 0                                     |
| Mercury-containing components                                                   | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0                                     |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm             | Includes background illuminated displays with gas discharge lamps panel*1  | 1                                     |
| Cathode Ray Tubes (CRT)                                                        |                                                                      | 0                                     |
| Capacitors / condensers (Containing PCB/PCT)                                   |                                                                      | 0                                     |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | C605 in SPS board                                                        | 1                                     |
| External electrical cables and cords                                           | HDMI cable*1, DP cable*1, VGA cable*1, Power                          | 4                                     |

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Template Revision C

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HPI instructions for this template are available at [EL-MF877-01](#)
### Item Description | Notes | Quantity of items included in product
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Gas Discharge Lamps |  | 0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) |  | 0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0
Components and waste containing asbestos |  | 0
Components, parts and materials containing refractory ceramic fibers |  | 0
Components, parts and materials containing radioactive substances |  | 0

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
--- | ---
Screwdriver | 2 |
Slothead screwdriver | 1 |

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Push the button of stand to unlock the stand, then pull out the stand form the monitor head.
2. Use screwdriver to separate the RC from the monitor head through the tear down slots which on the bottom side.
3. Remove the adhesive tape on the panel and unlock the back light wire*1 and LVDS*1 from the panel.
4. Disconnect FFC*1 from the interface board.
5. Pull out the control board and privacy board from the mid frame by hand.
6. Remove screws *9 on the panel and mid frame and screw*1 on the usb board.
7. Disconnect FFC from the board
8. Remove the mylar from the SHD
9. Remove screws *7 on the power board and interface board
10. Disconnect the wire to separate power board and interface board
11. Disconnect the LVDS from interface board.
12. Disconnect the wire from power board.

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3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Push the button of stand to unlock the stand, then pull out the stand from the monitor head.

2. Use screwdriver to separate the RC from the monitor head through the tear down slots which on the bottom side.
3. Remove the adhesive tape on the panel and unlock the back light wire*1 and LVDS*1 from the panel.

4. Disconnect FFC*1 from the interface board.

5. Pull out the control board and privacy board from the mid frame by hand.
6. Remove screws *9 on the panel and mid frame.

7. Disconnect FFC from the board.

8. Remove the mylar from the SHD

9. Remove screws *7 on the power board and interface board
10. Disconnect the wire to separate power board and interface board

11. Disconnect the LVDS from interface board.

12. Disconnect the wire from power board.